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Amendments to the Specification

Please amend paragraphs [0018] and [0029], as follows:

[0018] The entire setup 10 is placed in a vacuum chamber (not shown).

Preferably, the interior surface of the tubular structure is first cleaned to remove superficial contaminants. An inert gas, such as argon gas, is backfilled into the chamber to a pressure of about 0.5 to about 100 millitorr, preferably about 15 millitorr. A pulse frequency of from about 1 Hz to about 20 kHz, preferably from about 2 kHz to about 3 kHz, at a pulse width of from about 5 microseconds to about 40 microseconds, preferably about 20 microseconds, is applied to bias the tube to at least about 200V, preferably about 4 kV (using bias voltage means represented by V in FIG. 1B), for a duration necessary to deposit a coating having the desired thickness. Preferably, from about 5 minutes to about 60 minutes, most preferably for about 30 minutes.

[0029] The entire setup 20 is placed in a vacuum chamber (not shown).

Preferably, the interior surface of the tube is first cleaned to remove superficial contaminants. An inert gas, such as argon gas, or a combination of argon gas and H₂ is backfilled into both the chamber and the tube to a pressure of about 0.5 to about 100 millitorr, preferably about 15 millitorr. In one method, as the magnetic assembly is grounded to the vacuum chamber, a pulse frequency of from about 1 Hz to about 20 kHz, preferably from about 2 kHz to about 3 kHz, at a pulse width of from about 5 microseconds to about 40 microseconds, preferably about 20 microseconds, is applied to negatively bias the tube (using a bias voltage means such as V in FIG. 2) to at least about

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200V, preferably about 4kV, for a duration necessary to generate plasma within the tube. Preferably, from about 1 minute to go most preferably for about 30 minutes. Herein, Ar ions are drawn to the inner surface of the tube resulting in sputter cleaning. The use of argon and a reactive gas such as H₂ allows for effective removal of oxides and other organic contaminants from the inner diameter of the tube.